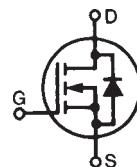


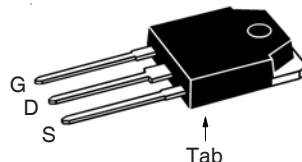
**PolarP2™ HiperFET™
Power MOSFET**
IXFQ24N50P2

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Diode



V_{DSS} = 500V
I_{D25} = 24A
R_{DS(on)} ≤ 270mΩ
t_{rr(typ)} ≤ 200ns

TO-3P



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	500	V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ	500	V
V _{GSS}	Continuous	± 30	V
V _{GSM}	Transient	± 40	V
I _{D25}	T _C = 25°C	24	A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	50	A
I _A	T _C = 25°C	12	A
E _{AS}	T _C = 25°C	750	mJ
dv/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 150°C	15	V/ns
P _D	T _C = 25°C	480	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
T _L	Maximum Lead Temperature for Soldering	300	°C
T _{SOLD}	Plastic Body for 10s	260	°C
M _d	Mounting Torque	1.13/10	Nm/lb.in.
Weight		5.5	g

Symbol	Test Conditions (T _J = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 250μA	500		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 1mA	2.5		4.5 V
I _{GSS}	V _{GS} = ± 30V, V _{DS} = 0V			± 100 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C			25 μA 1 mA
R _{DS(on)}	V _{GS} = 10V, I _D = 0.5 • I _{D25} , Note 1			270 mΩ

Features

- Avalanche Rated
- Fast Intrinsic Diode
- Dynamic dv/dt Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- Laser Drivers
- AC and DC Motor Drives
- Robotics and Servo Controls

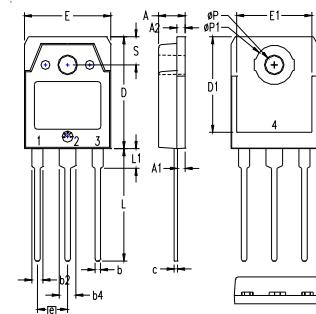
Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)		Characteristic Values		
			Min.	Typ.	Max.
g_{fs}	$V_{DS} = 20V, I_D = 0.5 \cdot I_{D25}$, Note 1	14	24	S	
C_{iss}		2890		pF	
C_{oss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	280		pF	
C_{rss}		22		pF	
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$ $R_G = 10\Omega$ (External)	15		ns	
t_r		9		ns	
$t_{d(off)}$		30		ns	
t_f		5		ns	
$Q_{g(on)}$		48		nC	
Q_{gs}	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	13		nC	
Q_{gd}		16		nC	
R_{thJC}			0.26	°C/W	
R_{thCS}		0.25		°C/W	

Source-Drain Diode

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)		Characteristic Values		
			Min.	Typ.	Max.
I_s	$V_{GS} = 0V$			24	A
I_{SM}	Repetitive, Pulse Width Limited by T _{JM}			96	A
V_{SD}	$I_F = I_S, V_{GS} = 0V$, Note 1			1.3	V
t_{rr}	$I_F = 12A, -di/dt = 100A/\mu s$		200	ns	
I_{RM}		10		A	
Q_{RM}	$V_R = 100V, V_{GS} = 0V$	0.69			μC

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

TO-3P (IXFQ) Outline



1 - GATE
2 - DRAIN (COLLECTOR)
3 - SOURCE (EMITTER)
4 - DRAIN (COLLECTOR)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.799	19.80	20.30
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e	.215	BSC	5.45	BSC
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
ØP	.126	.134	3.20	3.40
ØP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

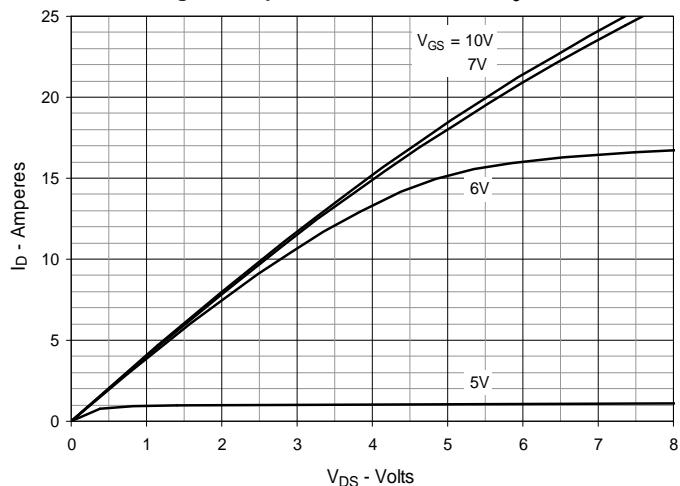
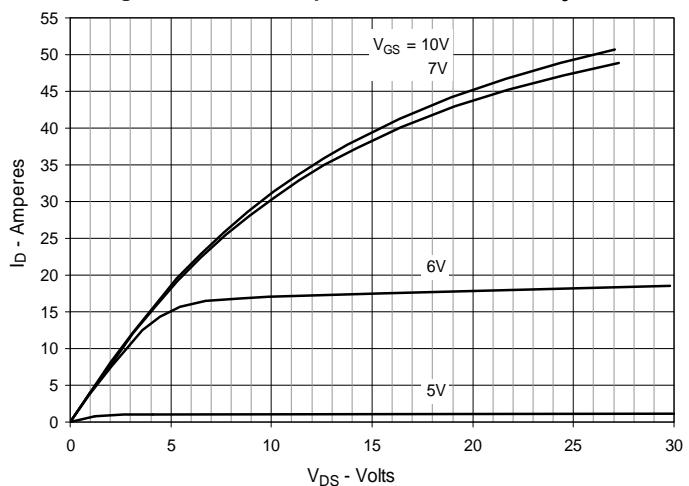
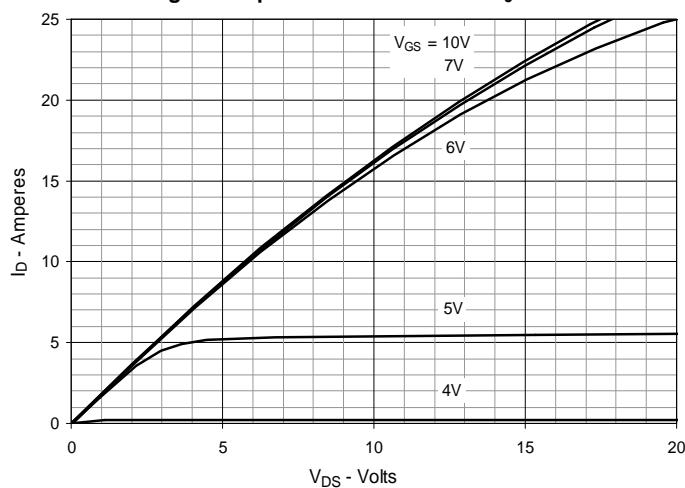
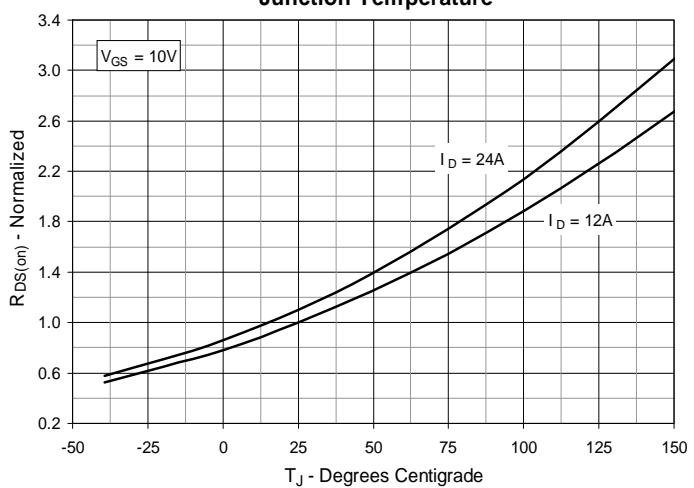
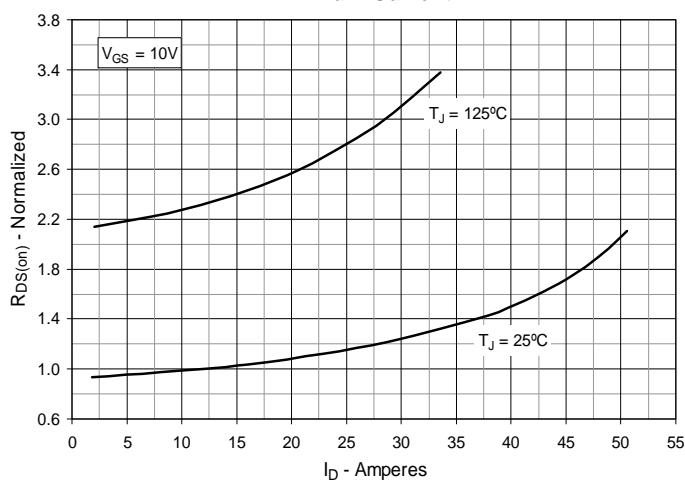
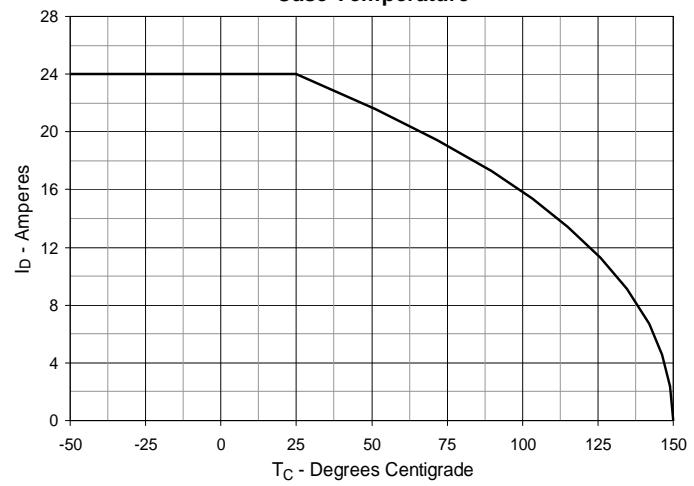
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ **Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$** **Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$** **Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 12\text{A}$ Value vs. Junction Temperature****Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 12\text{A}$ Value vs. Drain Current****Fig. 6. Maximum Drain Current vs. Case Temperature**

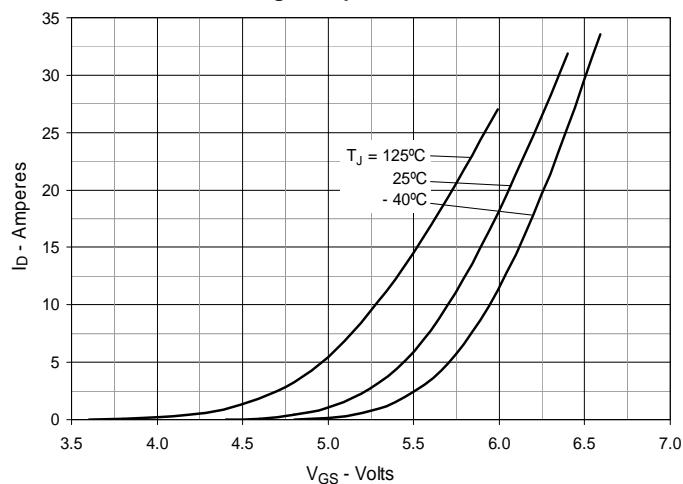
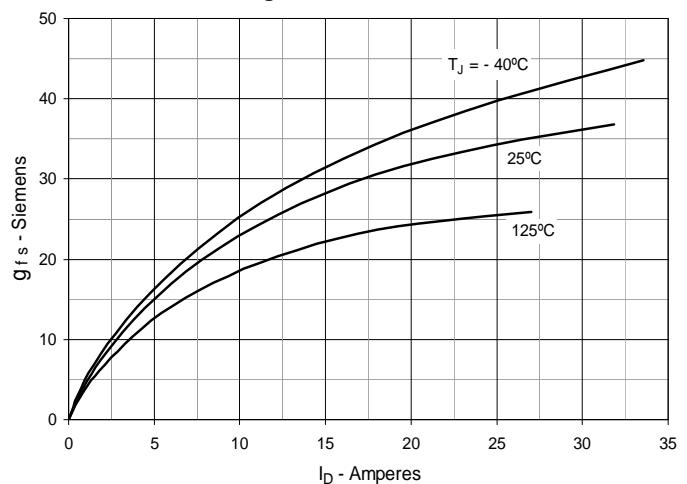
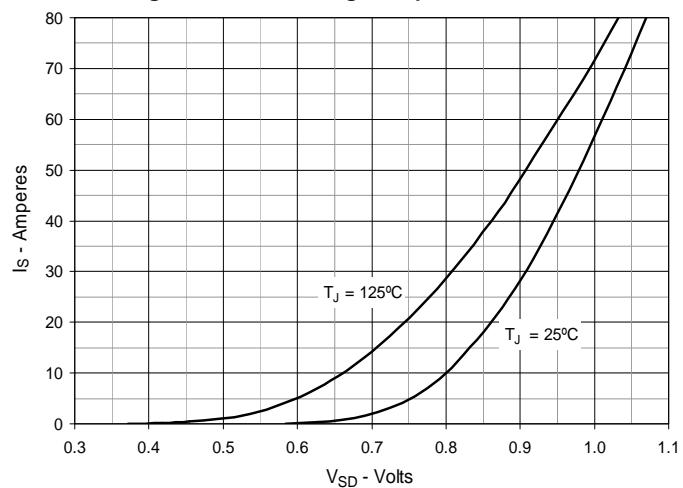
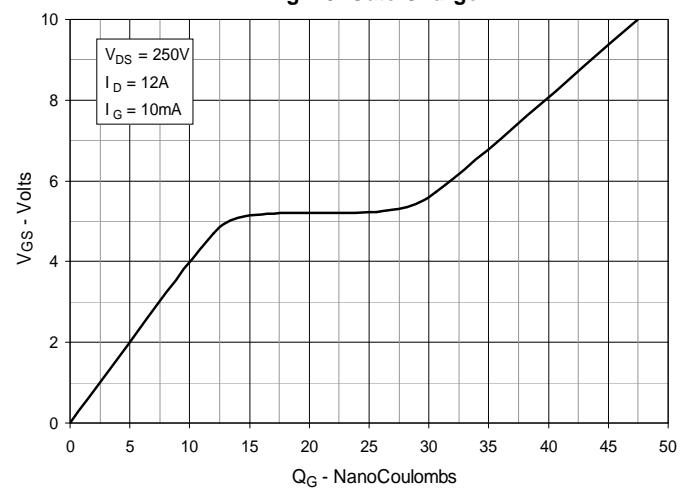
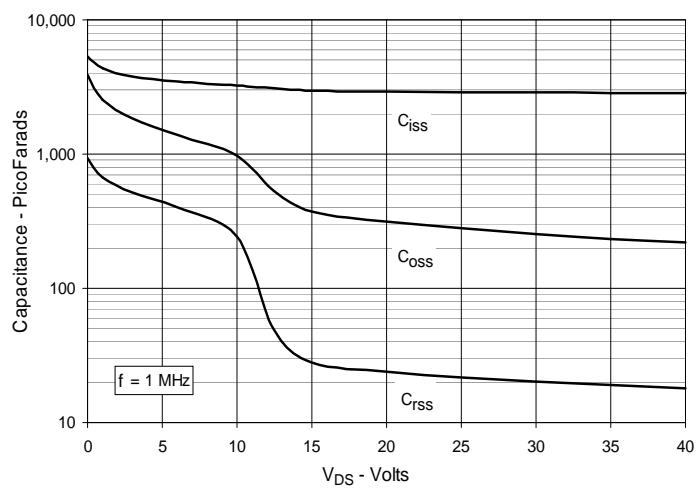
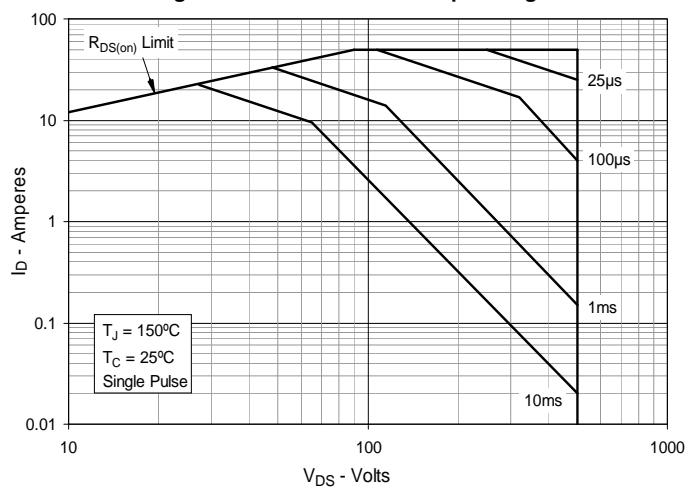
Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Forward Voltage Drop of Intrinsic Diode****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Forward-Bias Safe Operating Area**

Fig. 13. Maximum Transient Thermal Impedance